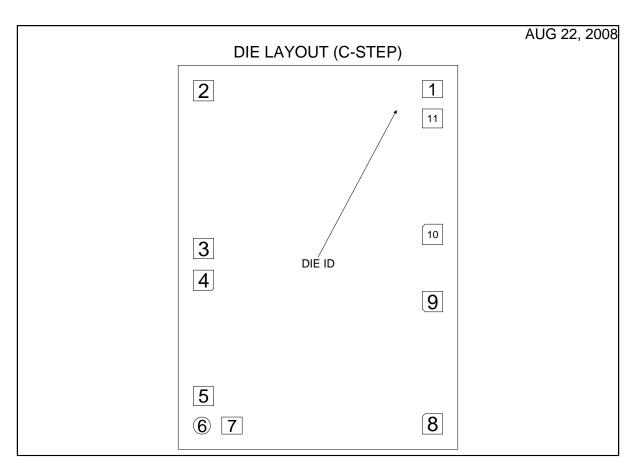


# LM119 MDR MCD2910A HIGH SPEED DUAL COMPARATOR



### DIE/WAFER CHARACTERISTICS

DIE/WAFER CHARA	CTERISTICS		
Fabrication Attributes		General Die Information	
Physical Die	LM119C	Bond Pad Opening	109.22µm x 91.44µm
Identification		Size (min)	
Die Step	С	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	VOM ONLY
Wafer Diameter	150mm	Back Side Metal	BAREBACK
Die Size (Drawn)	1498.6µm x 2057.4µm	Back Side Connection	V -
	59.0mils x 81.0mils		
Thickness	330µm Nominal		
Min Pitch	157µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			



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### Die Bond Pad Coordinate Locations(C-Step) (Referenced to die center, coordinates in $\mu m$ ) NC = No Connection, N.U. = Not Used Signal Name Pad Number X/Y Coordinates Pad Size Χ Υ Χ Output 1 1 613 901 109 91 Х Gnd 1 2 892 -613 109 Х 109 +Input 1 3 -613 46 109 109 Χ 4 -Input 1 -123 109 109 -613 Х V-5 -613 -744 109 101 Х NC 6 91 -622 -901 91 Χ Output 2 7 109 91 -461 -901 Х Gnd 2 8 -892 109 109 613 Х +Input 2 9 613 -237 109 109 Х -Input 2 10 613 123 109 Х 109 V+ 11 744 109 613 101 Χ



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